

DS

1. : 2010 既

2. : DS

3. : 09 16 (水) 09 30 (水) 24

4.

Advanced Process Development

- Photolithography (including EUV, e-beam, OPC/RET) Photo Resist, Oxidation, Cleaning & CMP, Diffusion, Thin Film, CVD, Ion Implantation, Metallization, Metrology & Inspection, etc.

OPC : Optical Proximity Correction (Comput. Litho)

Module Development

- Device Isolation, Transistor, Capacitor, Dielectric
- High-K/Metal Gate, SD2/SDN Gate Dielectric
- Low-K, Interconnect, etc.

FEOL/BEOL Process Integration (DRAM/Flash/Logic, etc.)

New Memory : PRAM, STT-MRAM, ReRAM, etc.

TCAD/ECAD

- Process & Device Modeling, Material Modeling
- Circuit Compact/Reliability Modeling
- Circuit Simulator Development

Advanced CMOS Image Sensor(CIS) Development

- Pixel Design, Image Signal Processing, Mixed IC Design, Analog/Digital Design
- CIS Process Development

5.

Dearsamsung.co.kr - - DS

- " " (DS 1)

E-Mail

/ ()

6.

1 : () 2 : (/) 3 :

7.

: juyoung@samsung.com, 031-208-3907

: jh1982.park@samsung.com, 031-208-3888